

10 9 8 7 6 5 4 3 2 1

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53261-****	WAFER ASSY	MODEL NO./MATERIAL NO.
50079-****	TERMINAL	
51021-****	HOUSING	

RELEASED EC NO: J2006-2426 DRWN: A0YAGI 2006/02/02 CHKD: YMAEDA 2006/02/03 APPR: NUKITA 2006/02/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	± ---	DRAWN BY Y. A0YAGI	DATE 2006/01/30	TITLE 1.25 W-TO-B CONN. 51021,53261 MATING CROSS SECTION			
	10 OVER 30 UNDER	± ---	CHECKED BY Y. MAEDA	DATE 2006/01/30	MOLEX INCORPORATED			
	30 OVER	± ---	APPROVED BY N. UKITA	DATE 2006/01/30	DOCUMENT NO. SD-51021-002			
	ANGULAR	± --- °	MATERIAL NO. SEE CHART		SHEET NO. 1 OF 1			
0	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

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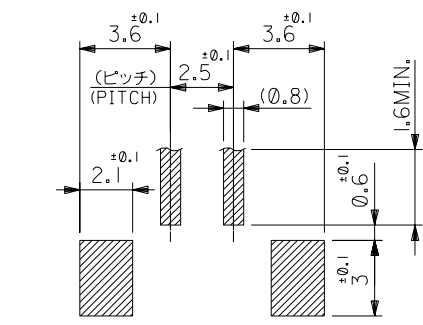
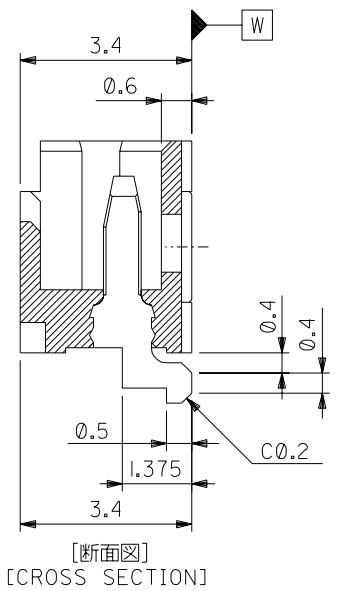
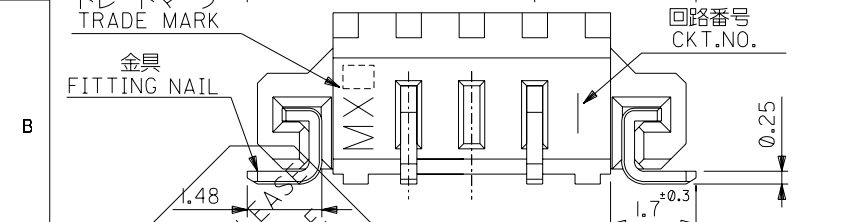
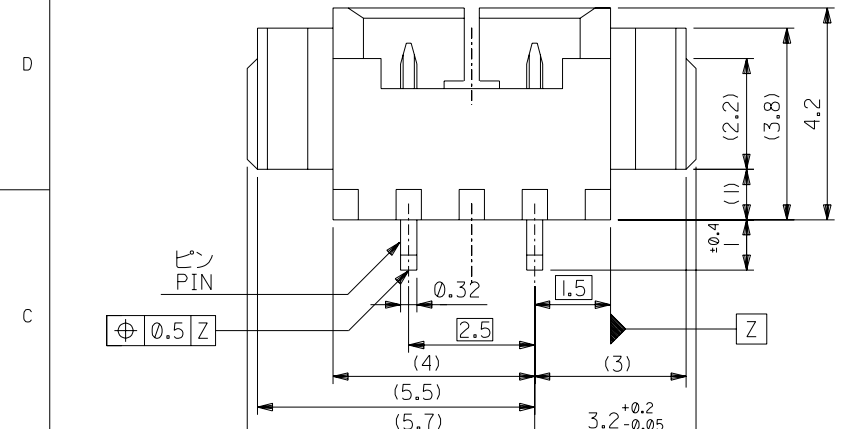
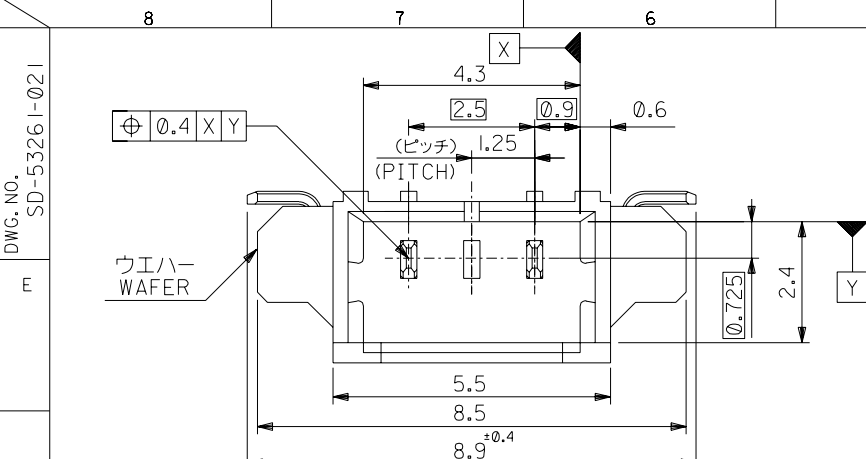
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参考基板レイアウト
RECOMMENDED P.C.BOARD PATTERN DIM.(REF.)
(SCALE 5:1)

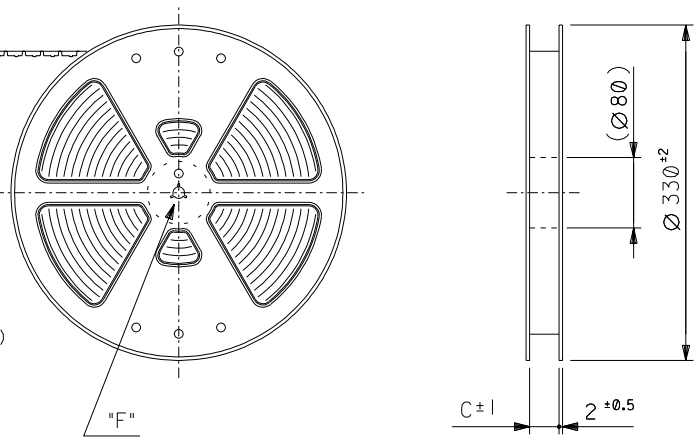
注記 NOTES

- 嵌合相手: 51021 シリーズ
MATES WITH: 51021 SERIES
- 材質 MATERIAL
ウエハー: NYLON46, UL94V-0
WAFER
ピン: リン青銅, ニッケル下地, スズメッキ
PIN: PHOS-BRO., TIN OVER NICKEL PLATING
金具: リン青銅, ニッケル下地, スズメッキ
FITTING NAIL: PHOS-BRO., TIN OVER NICKEL PLATING
- ソルダーテール部のズレ量及び金具(補強板)のズレ量は基準面 [W] に対し、上方向 0.05 MAX.、下方向に 0.1 MAX. とする。
OFFSET BETWEEN BASIS PLANE [W] TO SOLDER TAIL BOTTOM AND FITTING NAIL BOTTOM:
UPPER SIDE: 0.05MAX.
LOWER SIDE: 0.1MAX.

DO NOT SCALE DRAWING

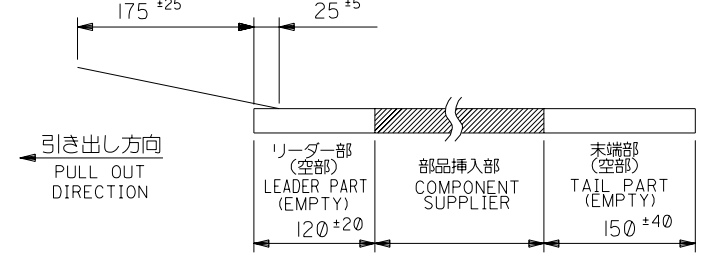
EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	RELEASED ECNNO. J2004-2236 DRWN: A.IDA 04/02/03 CHK: H.TAKASE APPR: J.MIYAZAWA	MATERIAL 材料 注記参照 SEE NOTES FINISH 仕上げ 注記参照 SEE NOTES	GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差 10 UNDER 未滿 ±0.2 10 OVER 以上 30 UNDER 未滿 ±0.25 30 OVER 以上 ±0.3 ANGLE 角度 ±3°	SCALE 10-1 DESIGN UNITS <input checked="" type="checkbox"/> mm <input type="checkbox"/> INCH DRAWN BY & DATE A. Iida 04/02/03 CHECKED BY & DATE H. Takase 04/02/03 APPROVED BY & DATE J. Miyazawa 04/02/03 CAD FILENAME SD-53261-021.S01	DIMENSIONS: <input type="checkbox"/> mm <input type="checkbox"/> INCH <input checked="" type="checkbox"/> mm <input type="checkbox"/> INCH ONLY SHT REV REVISE ON CAD ONLY	TITLE: 1.25 WIRE TO BOARD CONN. WAFER ASS'Y FOR SMT RIGHT ASNGLE -LEAD FREE- MOLEX MOLEX INCORPORATED MATERIAL NO. 53261-0329 DRAWING NO. SD-53261-021 SHEET NO. 1 OF 1	
PRE-RELEASED REFERENCE USE ONLY							WIRE RANGE 適用線径範囲 #	INS. RANGE 被覆外径 #	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.		

引き出し方向
PULL OUT DIRECTION

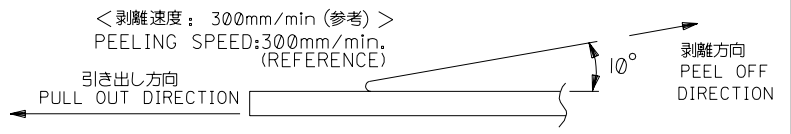


注記
NOTES

- 53261-**29 の詳細寸法については図面 SD-53261-021 を参照下さい。
RE DETAILED DIMENSIONS, SEE SD-53261-021.
- 梱包数量: 1000個/リール
NUMBER OF CONNECTOR: 1000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH
トップテープリーダ部 TOP TAPE LEADER PART 175⁺²⁵
トップテープ未接着部 TOP TAPE NON-BONDED PART 25⁺⁵



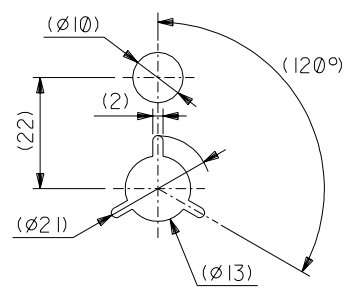
- トップテープの剥離強度: 0.1N~1.3N(10~130gf) (剥離方向は下図参照)
PEELING OFF FORCE OF TOP TAPE: 0.1N~1.3N(10~130gf)
(PEELING DIRECTION IS SHOWN IN FOLLOWING FIG.)



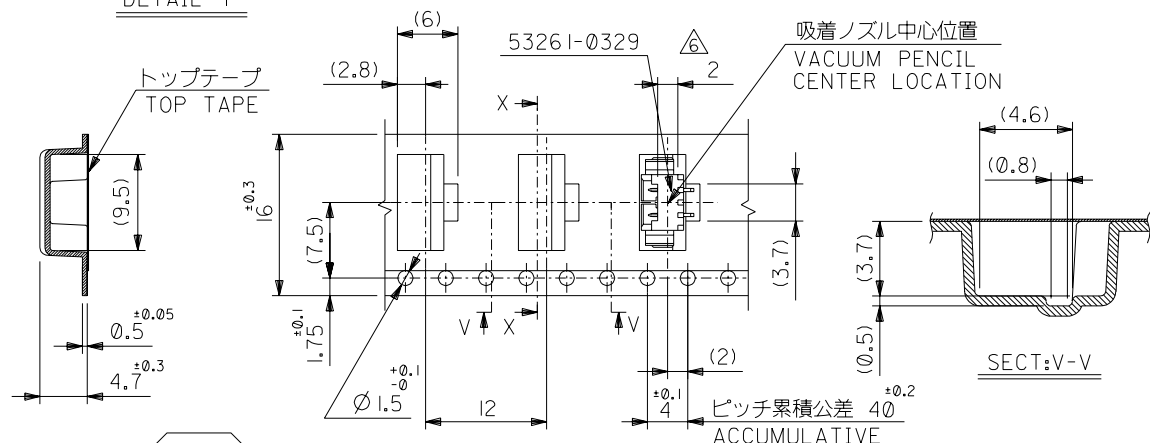
- 材料 (MATERIAL)
キャリアテープ(CARRIER TAPE): ポリプロピレン (POLYPROPYLENE)
トップテープ (TOP TAPE): PET, PE, PEF
リール (REEL): ポリスチレン (PS) <リサイクル材含む>
POLYSTYRENE(PS) <RECYCLE MATERIAL CONTAINED>

△ コネクタ、ハウジング平面部
CONNECTOR, HOUSING FLAT AREA

DETAIL "F"



吸着ノズル中心位置
VACUUM PENCIL CENTER LOCATION



SECT: V-V

SECT: X-X

引き出し方向
PULL OUT DIRECTION

PRE-RELEASE
REFERENCE
USE ONLY

EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	RELEASED	MATERIAL 材料	GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差	SCALE	DESIGN UNITS <input checked="" type="checkbox"/> mm <input type="checkbox"/> INCH	THIRD ANGLE PROJECTION	DIMENSIONS:		SHT	REV
					ECNNO. J2004-2236						FINISH 仕上げ	10 UNDER 未満		
DRWN: A.JIDA CHK: H.TAKASE APPR: J.MIYAZAWA	DRWN: A.JIDA CHK: H.TAKASE APPR: J.MIYAZAWA	DRWN: A.JIDA CHK: H.TAKASE APPR: J.MIYAZAWA	DRWN: A.JIDA CHK: H.TAKASE APPR: J.MIYAZAWA	DRWN: A.JIDA CHK: H.TAKASE APPR: J.MIYAZAWA	DESCRIPTION	WIRE RANGE 適用層被範囲	30 UNDER 未満	±0.2	DRAWN BY & DATE A.Jida 04/02/03	CHECKED BY & DATE H.Takase 04/02/03	TITLE: 1.25 WIRE TO BOARD CONN. WAFER ASS'Y FOR SMT EMBOSSED TAPE PACKAGE -LEAD FREE-			
					0									
注記参照 SEE NOTES											MOLEX INCORPORATED			
注記参照 SEE NOTES														
CAD FILENAME SD-53261-022.S01								MATERIAL NO. 53261-0372	DRAWING NO. SD-53261-022	SHEET NO. 1 OF 1				
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.												SIZE B		